

Docket No.: MAS-FIN-128

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : HARRY HEDLER ET AL.
Filed : CONCURRENTLY HEREWITH
Title : ELECTRONIC COMPONENT WITH A SEMICONDUCTOR CHIP
AND METHOD OF PRODUCING THE ELECTRONIC
COMPONENT

31000 U.S. PTO
10/056356
01/24/02

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent 5,879,964 (Paik et al.), dated March 9, 1999;

German Published Non-Prosecuted Patent Application DE 197 28 992 A1 (Lee), dated January 14, 1999, frame for at least one semiconductor.

Patent Abstracts of Japan 10 316 955 A (Koichiro et al.), dated December 2, 1998;

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,


For Applicants

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Date: January 24, 2002

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